



033792R003

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Lei LU, et al.

U.S. Serial No.: 10/532,674

Group Art Unit: To Be Assigned

Filed: : April 26, 2005

Examiner: To Be Assigned

For: NANO-TWIN COPPER MATERIAL WITH ULTRAHIGH STRENGTH AND  
HIGH CONDUCTIVITY AND ITS PREPARATION METHOD

**SECOND INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

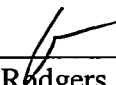
Pursuant to the duty of disclosure under 37 C.F.R. 1.56, Applicants are enclosing an Information Disclosure Citation Form (PTO-1449) and copies of the non-U.S. documents cited therein.

It is respectfully requested that the cited documents be considered by the Examiner in the above-identified patent application and that the cited documents be made officially of record therein. It is further requested that a listing of the same appear on the face of any patent which may issue from this application.

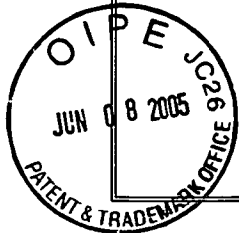
This Information Disclosure Statement is being filed within three (3) months of the filing date of the application. Therefore, it is believed that no fees are due under 37 C.F.R. Section 1.97(b)(3).

Respectfully submitted,  
SMITH, GAMBRELL & RUSSELL, LLP

By:

  
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Date: June 8, 2005



FORM PTO-1449	ATTY. DOCKET 033792R003	SERIAL NO. 10/532,674
INFORMATION DISCLOSURE STATEMENT		
APPLICANT: Lei LU, et al.		
FILING DATE April 26, 2005	GROUP ART UNIT <del>To Be Assigned</del> 1793	

#### U.S. PATENT DOCUMENTS

*Examiner's Initials		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	FILING DATE, IF APPROPRIATE
	AA						
	AB						
	AC						

#### FOREIGN PATENT DOCUMENTS

*Examiner's Initials		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION	
							YES	NO
/S.I./	AD	CN 1389597A	1/8/03	China			ABS	
/S.I./	AE	CN 1181224C	12/22/04	China				
/S.I./	AF	CN 1337475A	2/27/02	China				
/S.I./	AG	CN 1105398A	7/19/95	China				
	AH							
	AI							
	AJ							
	AK							
	AL							

#### OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.)

/S.I./	AM	P.G. Sanders, et al., "Elastic and Tensile Behavior of Nanocrystalline Copper and Palladium", Acta Mater, Vol. 45, No. 10, pp. 4019-4025 (1997)
/S.I./	AN	R. Suryanarayanan, et al., "mechanical Properties of Nanocrystalline Copper Produced by Solution-Phase Synthesis", Journal of Materials Research, Vol. 11, No. 2, Feb. 1996, pp. 439-448
/S.I./	AO	M. Legros, et al., "Microsample Tensile Testing of Nanocrystalline Metals", Philosophical Magazine A, 2000, Vol. 80, No. 4, pp. 1017-1026
/S.I./	AP	Y.M. Wang, et al., "Microsample Tensile Testing of Nanocrystalline Copper", Scripta Mater, 48 (2003) pp. 1581-1586
/S.I./	AQ	R.K. Islamgaliev et al., "The Determination of the Grain Boundary Width of Ultrafine Grained Copper and Nickel from Electrical Resistivity Measurements", Phys. Stat. Sol. (a), 162, pp. 559-566 (1997)
/S.I./	AR	Notification Concerning Submission or Transmittal of Priority Document (Form PCT/IB/304) issued in connection with PCT/CN03/00867
EXAMINER:		DATE CONSIDERED:
/Sikyln lp/		06/18/2009
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>		